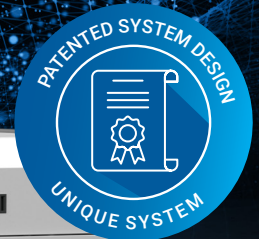


Heavy boards. Gently soldered.



The Vision RCC combines three technologies in a patented reflow soldering process for heavy, complex SMD assemblies up to 25 kg. For uniform heating, controlled soldering temperatures and low-void solder joints without carriers.

One profile for all products!

AI servers · 6G · Aerospace · Humanoid robotics · Power electronics



25 kg

Assembly weight with mixed components

210 °C

Vapour phase entry temperature, solder time halved

2 %

Void rate achievable with vacuum

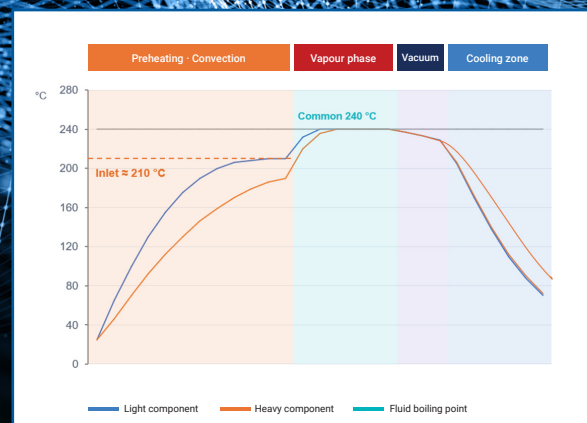
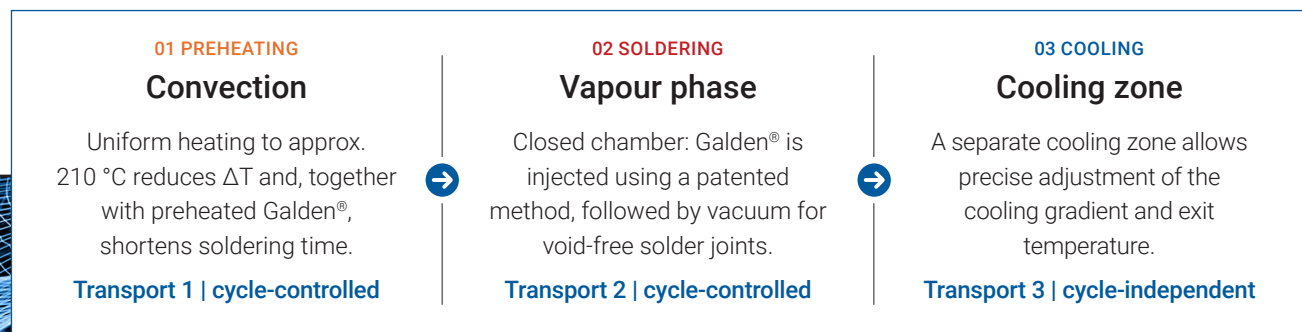
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Carriers: assemblies up to 25 kg conveyed directly

- ✓ **No overheating:** The boiling point physically limits the soldering temperature.
- ✓ **Closed loop:** Galden® is 100% purified after every soldering cycle, with minimal consumption.
- ✓ **Up to 25 kg:** Three conveyors carry heavy assemblies safely through all process steps.
- ✓ **Dual preheating, half the soldering time:** Assembly at approx. 210 °C, Galden® preheated.
- ✓ **Your choice of atmosphere:** Air or N₂ (<100 ppm O₂)
- ✓ **ViCON:** Intuitive touch control, automated workflows, MES, traceability and process analysis.

Three zones. Three conveyors up to 25 kg. Air or nitrogen.

The Vision RCC combines convection preheating, condensation and vacuum for gentle, reliable soldering of lightweight and heavy components.



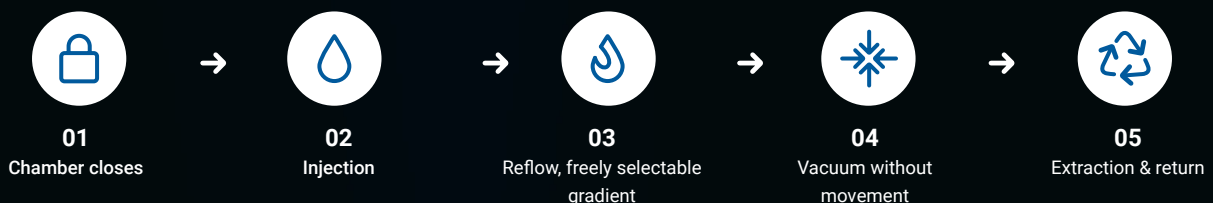
Physics works for you

In the vapour phase, no part of the assembly can exceed the boiling point of the heat transfer fluid. Lightweight components reach this limit first and stay there while heavy components catch up. The result: minimal ΔT without overheating.

- › Assembly 210 °C, Galdden® preheated: solder time halved
- › Heat transfer by condensation instead of hot gas
- › Protection of temperature-sensitive components

Soldering and vacuum in one chamber

The vacuum-tight chamber is maintained at a constant temperature. Preheated Galdden® evaporates on the chamber floor as it is injected. The quantity determines the freely selectable temperature gradient across the assembly. After soldering, Galdden® and residues on the product are extracted and returned to the reservoir. Vacuum follows immediately, without moving the product, achieving a void rate below 2%.



Test your heaviest assemblies.

At our application centres in China and Germany:
Screen printing, component placement, soldering, coating, SPI and X-ray.

www.rehm-group.com

